

Amendments to the Specification:

Please replace paragraph [0063] with the following amended paragraph:

[0063] Means of orientation 6 of the gripper arm shown in FIGs. 2 to 4 advantageously comprise a first beam 21 capable of being cut whenever notch 3 of wafer 2 is not opposite beam 21, and cutoff detector 23 of first beam 21. Beam 21 can, for example, be a preferably vertical beam of light emitted at a first selected location 50 by light-emitting diode 22 and the detector 23 a photosensitive cell placed opposite the light-emitting diode. Beam 21 can be placed in such a way that, during angular displacement of wafer 2 from the effect of drive roller 9, beam 21 can traverse notch 3 until it strikes photosensitive cell, beam 21 being in the opposite case cut by wafer 2. When the position of notch 3 has been identified by reception of beam 21 on photosensitive cell, wafer 2 is oriented by drive roller 9 with the desired angular value to place mark 3 in a predetermined position. Operation of roller 9 and photosensitive cell will at least be advantageously operated and controlled by a central unit (not shown) advantageously automated as a function of the operations to be carried out.

Please replace paragraph [0064] with the following amended paragraph:

[0064] The gripper arm shown in FIGs. 2 to 4 advantageously comprises means 21, 24 for identifying the position of semiconductor wafer 2 when it is placed in a support (not shown). The locator means provide optimal positioning of the gripper arm before seizure of semiconductor wafer 2. Identification consists in locating any two points on the periphery 4 of wafer 2 as it is grasped, for example, by means of the two beams 21 and 24 placed on structure 7 of the arm, and respectively describing the two points in a horizontal plane, as shown in FIG. 3 in the plane of the drawing. Beam 24 can, for example, be a light beam emitted by a light-emitting diode and the detector a photosensitive cell placed opposite the emitting diode. Locator means advantageously comprise first 21 beam and second 24 vertical beam placed at a selected location 52 a predetermined distance 54 cooperating with the first beam and a characteristic dimension of semiconductor wafer 2, in the example the outside diameter of the wafer, to

establish the position, within a horizontal plane, of the semiconductor wafer in the support (not shown).

Please replace paragraph [0067] with the following amended paragraph:

[0067] Alternatively and advantageously, locating means comprise a third beam (not shown) from a third optical emitter 60 and sensed by a third optical detector 61 positioned at a selected location 56 a predetermined distance 58 from said first and second optical detectors cooperating with the first 21 or second 24 beam and a dimension characteristic of the semiconductor wafer, its outside diameter in the example, to enable us to establish the position of the semiconductor wafer in its support when the first or second beam is placed opposite the notch used as a positioning marker. To this end the third beam is placed in any position that can be used to obtain the chord of an arc on the periphery of the wafer, in combination with that of the first or second beam, which is not placed opposite the notch, and determine the configuration of two points of a chord of an arc on the periphery of the wafer. In effect the notch generally penetrates the wafer by a non-negligible length and could consequently result in incorrect measurement of the arc and thus of the position of the wafer. The third beam is used to ensure that at least two beams will not be opposite the notch when obtaining a chord. The third beam can be realized similarly to the two first.